

## Final Product/Process Change Notification Document #: FPCN21435X

Issue Date: 25 August 2016

Title of Change:	Test Change from 3mV to 9mV for NCS37013MNTWG
Proposed first ship date:	30 November 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <tamara.olney@onsemi.com></tamara.olney@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change Part Identification:	Affected products will be identified with date code as well as identified with a "dash" at end of the device number on the part mark per customer request.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other
Change Sub-Category(s):  Manufacturing Site Change/ Manufacturing Process Chan	\times Shipping/Packaging/Marking
Sites Affected:  All site(s)  not applicable  ON Semiconductor site(s):  ON Pocatello, Idaho ON Carmona, Philippines  External Foundry/Subcon site(s)	
Description and Purpose:  Update CTstim Offset Voltage limit at both wafer sort and final test to +/-9 mV. Mark change is to add a dash to differentiate between 3mV and 9mV per customer request.	
List of Affected Standard Parts:	
NCS37013MNTWG	

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